

## Material Composition Data Sheet

<b>Contact Information</b>
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Manufacturer	Total mass of component specified in (g)	Package	Material name	Substance name	CAS NO	Content( %)	Substance mass (mg)
MCC	0.008	SOT-23	Wafer	Si	7440-21-3	100%	0.042
			Lead Frame	Cu	7440-50-8	99.05%	1.878
				Ag	7440-22-4	0.45%	
				Others	---	0.50%	
			Wire	Cu	7440-50-8	100.00%	0.010
				Mold Compound	Silica	60676-86-0	75.00%
			Epoxy Resin		25036-25-3	15.00%	
			Phenol Resin		9003-35-4	8.00%	
			Zinc Borate		1332-07-6	1.95%	
			Plating	Carbon BLACK	1333-86-4	0.05%	0.126
				Sn	7440-31-5	100.00%	

**Materials Disclosure Disclaimer:** Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee its accuracy or completeness.